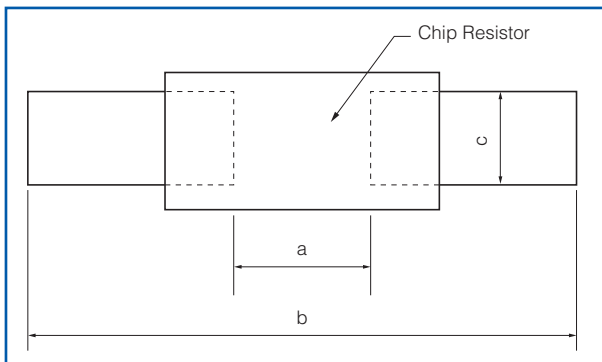## Recommended Land Pattern

● An example of a land pattern for the Rectangular Type is shown below.
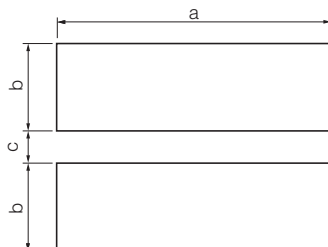

Size mm/inch	Dimensions (mm)		
	a	b	c
0402/01005	0.15 to 0.20	0.5 to 0.7	0.20 to 0.25
0603/0201	0.3 to 0.4	0.8 to 0.9	0.25 to 0.35
1005/0402	0.5 to 0.6	1.4 to 1.6	0.4 to 0.6
1608/0603	0.7 to 0.9	2.0 to 2.2	0.8 to 1.0
2012/0805	1.0 to 1.4	3.2 to 3.8	0.9 to 1.4
3216/1206	2.0 to 2.4	4.4 to 5.0	1.2 to 1.8
3225/1210	2.0 to 2.4	4.4 to 5.0	1.8 to 2.8
4532/1812	3.3 to 3.7	5.7 to 6.5	2.3 to 3.5
5025/2010	3.6 to 4.0	6.2 to 7.0	1.8 to 2.8
6432/2512	5.0 to 5.4	7.6 to 8.6	2.3 to 3.5
6432/2512*	3.6 to 4.0	7.6 to 8.6	2.3 to 3.5

＊ ERJL1W

High power (double-sided resistive elements structure) type

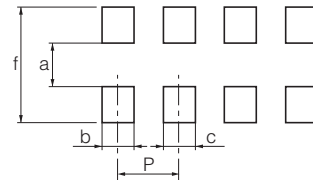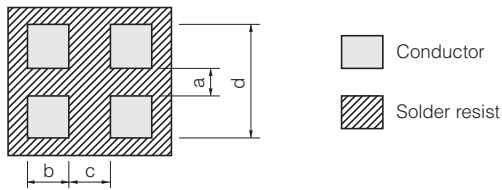| Part No.	Size mm/inch	Dimensions (mm)		
		a	b	c
ERJ2LW/2BW	1005/0402	0.52	1.4 to 1.6	0.4 to 0.6
ERJ3LW/3BW	1608/0603	0.5 to 0.8	2.5 to 2.7	0.9 to 1.1
ERJ6LW	2012/0805	0.6 to 0.8	3.2 to 3.8	1.1 to 1.4
ERJ6BW	2012/0805	0.9	3.2 to 3.8	1.1 to 1.4
ERJ6CW (10 to 13 mΩ)	2012/0805	0.7 to 0.9	3.2 to 3.8	1.1 to 1.4
ERJ6CW (15 to 30 mΩ)	2012/0805	0.9 to 1.1	3.2 to 3.8	1.1 to 1.4
ERJ8BW ERJ8CW (10 to 16 mΩ)	3216/1206	1.2	4.4 to 5.0	1.3 to 1.8
ERJ8CW (18 to 50 mΩ)	3216/1206	2.0 to 2.6	4.4 to 5.0	1.2 to 1.8

● An example of a land pattern for High Power Chip Resistors / Wide Terminal Type is shown below.

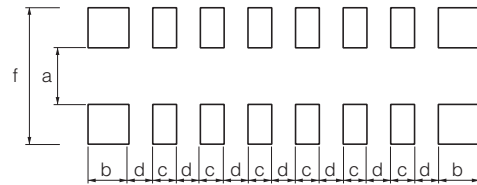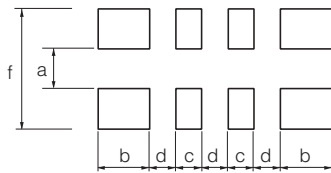| Part No.	Dimensions (mm)		
	a	b	c
ERJA1	6.4	1.70	0.60
ERJB1 ERJC1[1] ERJD1[2]	5.0	1.30	0.75
ERJB2 ERJD2[2]	3.2	0.95	0.70
ERJB3	2.0	0.80	0.60

(1) Anti-Sulfurated High Power Chip Resistors / Wide Terminal Type
(2) Low TCR High Power Chip Resistors / Wide Terminal Type

● An example of a land pattern for Chip Resistor Array, Anti-Sulfurated Chip Resistor Array and Chip Attenuator is shown below.

| Conductor |
| Solder resist |

Part No.	Dimensions (mm)			
	a	b	c	d
EXB14V EXB14A	0.30	0.30	0.30	0.80 to 0.90
EXB24V EXBU24 EXB24A	0.5	0.35 to 0.40	0.30	1.4 to 1.5

Part No.	Dimensions (mm)				
	a	b	c	f	P
EXB18V	0.20 to 0.30	0.15 to 0.20	0.15 to 0.20	0.80 to 0.90	0.40
EXBV4V,V8V	0.7 to 0.9	0.4 to 0.45	0.4 to 0.45	2 to 2.4	0.80
EXB34V,38V EXBU34,U38	0.7 to 0.9	0.4 to 0.5	0.4 to 0.5	2.2 to 2.6	0.80
EXBS8V	1 to 1.2	0.5 to 0.75	0.5 to 0.75	3.2 to 3.8	1.27

Part No.	Dimensions (mm)				
	a	b	c	d	f
EXB28V EXBU28	0.40	0.525	0.25	0.25	1.40
EXBN8V	0.45 to 0.50	0.35 to 0.38	0.25	0.25	1.40 to 2.00

Part No.	Dimensions (mm)				
	a	b	c	d	f
EXB2HV EXBU2H	1.00	0.425	0.25	0.25	2.00

● An example of a land pattern for Chip Resistor Networks is shown below.

EXBA	EXBE
For popular pattern	Pitch 1.27 mm	Pitch 0.8 mm
For high density pattern*	Pitch 0.635 mm Through-hole less	Pitch 0.4 mm Through-hole less

EXBD	EXBQ
For popular pattern	Pitch 0.635 mm	Pitch 0.5 mm

∗ When designing high density land patterns, examine the reliability of isolation among the lines and adopt the chip resistor networks.